REMARKS

Entry of this amendment in supplement to the previously filed Amendments of July 19, 2005, July 13, 2005, and April 7, 2005 is respectfully requested.

Appreciation is expressed to Examiner Williams for his courtesy and helpfulness during a personal interview conducted on July 27, 2005 between Mr. Williams and the undersigned attorney (noting that Messrs. Yaguchi, Noguchi, Takashima and Okabe were also in attendance at the interview). During the course of this interview, the current status of various recently filed papers was discussed. At that time, it was noted that, to applicants knowledge, all requirements for allowance of the application have now been met in this reissue application. For example, the Status of Claims and Support for Claim Changes filed on July 19, 2005 meets the requirement for explaining claim changes from the April 7, 2005 amendment by way of a separate paper. The Second Supplemental Amendment filed on July 19, 2005 amends the Specification to identify all of the Reissue applications presently pending in this matter. It is noted that the status of the recently filed Continuation Applications has been updated by the present amendment.

In addition to the general discussion regarding the recently filed papers, the patentability of independent claims 91 and 96 and their dependent claims was again discussed. At that time, it was noted that each of these independent claims specifically defines a substrate "formed of a glass fiber impregnated with resin", and that this serves as a clear distinction over the Hinrichsmeyer, which is the only remaining ground of rejection from the January 27, 2005 Office Action (noting that the other grounds of rejection have been overcome by the filing of a sworn

translation of the priority documents in this matter with the April 7, 2005 amendment). Concerning this, it is pointed out that column 6, lines 51 et seq. of the original U.S. Patent 5,777,391 for which this reissue application has been filed explains the significance of using a rigid substrate of glass fiber impregnated with resin. It was noted that claims 91 and 95 are directed to the concept of impregnating the glass fiber with resin, as opposed to limiting the invention to a specific resin (such as the examples of polyimide resin, epoxy resin and maleimide resin noted in the Specification). As explained beginning in column 6, line 55 of the original U.S. Patent for which this reissue application has been filed, the rigid substrate formed by the glass fiber impregnated with resin has a high young's modulus compared with prior art flexible substrates made of polyester or polyimide film. In addition, as noted in column 6, line 58 et seq,:

"The rigid substrate [made of glass fiber impregnated with resin] has a small thermal expansion coefficient in a planar direction."

Examples of the rigid substrate made of glass fiber impregnated with resin are then discussed in column 6, lines 60 et seq. As also noted during the interview, these advantages of a small thermal expansion coefficient provides for a better mounting compatibility for the rigid substrate on an underlying substrate in arrangements shown, for example, in Fig. 10 since the thermal expansion coefficients are similar between the rigid substrate and the underlying substrate. Still further, it was noted that these advantages can be achieved at a lower cost than arrangements such as using ceramic substrates (as found in the Hinrichsmeyer reference).

In addition to the above discussion, it was pointed out that Hinrichsmeyer completely fails to teach or suggest a substrate formed of glass fiber impregnated

with resin. Quite to the contrary, as noted in column 2, line 38 et seq. of the Hinrichsmeyer reference:

"The chip carrier 10 is preferably made of a reinforced polyimide or ceramic material."

Absolutely noting in Hinrichsmeyer teaches or suggests forming a substrate of glass fiber impregnated with resin. Therefore, as noted during the interview, it is urged that independent claims 91 and 96, together with their dependent claims, are clearly patentably distinct from the Hinrichsmeyer reference, whether considered alone or in combination with other prior art of record.

By the present amendment, new claims 102 and 103 are presented for examination. These new claims specifically define that the substrate is a rigid substrate. This corresponds to the above discussion noted from column 6, lines 51 et seq concerning the advantages of a rigid substrate formed of glass fiber impregnated with resin. As such, these new claims 102 and 103 even further define over the cited prior art to Hinrichsmeyer and reconsideration and allowance of these dependent claims, together with the independent claims 91 and 95 is respectfully requested.

If the Examiner believes that there are any other points which may be clarified or otherwise disposed of either by telephone discussion or by personal interview, the Examiner is invited to contact Applicants' undersigned attorney at the number indicated below.

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paper to the Deposit Account of Antonelli, Terry, Stout & Kraus, LLP, Dep. Acct. No. 01-2135 (1374.34189R00), and please credit any excess fees to such deposit account.

Very truly yours,

Antonelli, Terry, Stout & Kraus, LLP

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